

# APPROVAL SHEET

# WLCW2012HQ SMD Wire Wound Ceramic Chip Inductors (High Q)

\*Contents in this sheet are subject to change without prior notice.



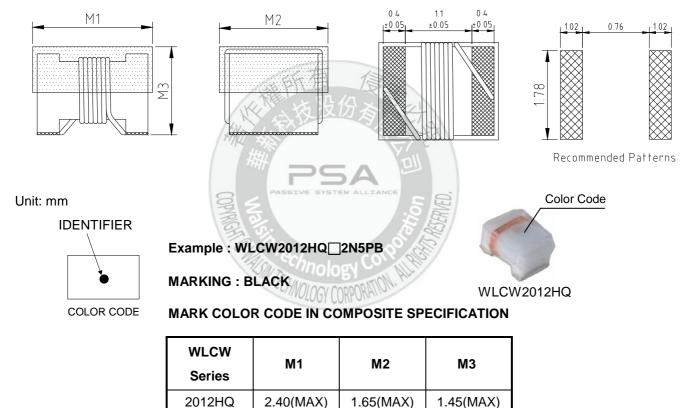
#### **Features**

- 1. Standard chip size bobbin with wire wound coil provides high reliability, productivity and performance.
- 2. WLCW2012HQ Series offers higher Q factors. In addition, current handling has been improved with significantly lower DCR values. Like all wire wound ceramic chip inductors, the WLCW2012HQ Series provides exceptional SRFs, tight inductance tolerance and batch consistency.
- 3. Wide range inductance and various tolerance options.
- 4. RoHS compliant.

# **Applications**

- 1. Communication: GSM/3G/LTE, Wi-Fi, GPS.
- 2. Consumer: Cabel/Terrestrial/BS Tuner, Bluetooth, Wireless Audio, Remote control.
- 3. M2M: ZigBee, Proprietary wilreless.

# **Shape and Dimension**



#### **Ordering Information**

WL	CW	2012	HQ	J	2N5	Р	В
Product Code	Series	Dimensions	Series extension	Tolerance	Value	Packing Code	
WL: Inductor	SMD wire wound ceramic chip inductor.	2012 (EIA 0805)	HQ: Higher Q & Lower DCR	G: ± 2% J: ± 5%	2N5 =2.5nH 12N=12nH	P=7" Reeled (Embossed tape)	B:STD



#### **Electrical Characteristics**

#### WLCW2012HQ series

Walsin Part Number	L (nH)	Tolerance	Measuring Frequency (MHz)	Q (Min)	Test Freq (MHz)	SRF (GHz) Min	RDC Max ( mOHM )	Irms (mA)	Color Code
WLCW2012HQ_2N5PB	2.5	J	250	80	1500	10.30	20	1.6	Black
WLCW2012HQ□5N6PB	5.6	J	250	98	1500	6.10	35	1.6	Brown
WLCW2012HQ□6N2PB	6.2	J	250	88	1000	4.75	35	1.6	Red
WLCW2012HQ_12NPB	12	G 、 J	250	80	1000	3.00	45	1.6	Orange
WLCW2012HQ_16NPB	16	G 、 J	250	72	500	2.95	60	1.5	Yellow
WLCW2012HQ_18NPB	18	G 、 J	250	75	500	2.55	60	1.4	Green
WLCW2012HQ 20NPB	20	G 、 J	250	70	500	2.05	55	1.4	Blue
WLCW2012HQ□27NPB	27	G 、 J	250	75	500	2.00	70	1.3	Violet
WLCW2012HQ□30NPB	30	G 、 J	250	65	500	1.95	95	1.2	Gray
WLCW2012HQ_39NPB	39	G 、 J	250	65	500	1.60	110	1.1	White
WLCW2012HQ□48NPB	48	G 、 J	200	65	500	1.40	95	1.2	Black
WLCW2012HQ□51NPB	51	G 、 J	200	65	500	1.40	120	1.0	Brown

Tolerance :  $J : \pm 5\% \setminus G : \pm 2\%$ 

OPERATING TEMPERATURE : -40°C ~ 125°C

L \ Q :TESTED BY AGILENT 4287A with 16197A or its equivalent

SRF: TESTED BY HP 8753E or HP4291B with 16193A or its equivalent

DCR: TESTED BY AGILENT 4338B or its equivalent





#### **RELIABILITY PERFORMANCE**

**Reliability Experiment For Electrical** 

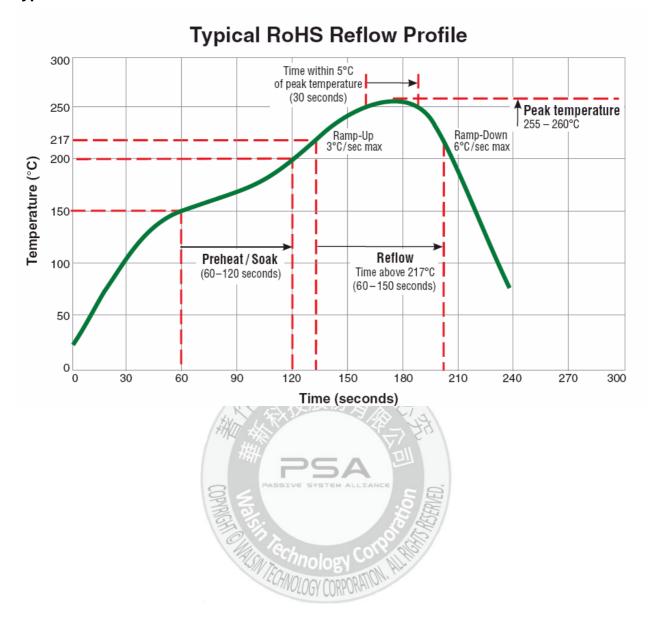
Test Item	Test Condition	Standard Source
Humidity Test	+40°C ± 2°C, humidity of 90% ± 5% (total 96 hours).	MIL-STD-202G Method 103B Test Condition B
High Temperature Test	1.Temperature: +125℃±2℃ 2.Test time: 48±2hrs	IEC 68-2 Test Condition B
Low Temperature Test	1.Temperature: -40°C±2°C 2.Test time: 48±2hrs	IEC 68-2 Test Condition A
Thermal Shock	+125°C±5°C (30 minutes) ~ -40 ± 5°C (30 minutes), temperature switch time: 5 minutes (total 50 cycles).	MIL-STD-202G Method 107G Test Condition B- 2
Life Test	+70℃±5℃ (250Hours)	MIL-STD-202G Method 108A Test Condition B

Reliability Experiment For Physical

Test Item	Test Condition	Standard Source
Vibration Test	10-55-10HZ, amplitude: 1.5mm, direction: X, Y, Z axes, each axis 2 hours (total 6 hours).	MIL-STD-202G Method 201A
Solder Heat Resistance Test	IR/convection reflow:Peak Temp 250±5℃ for 5Sec in air, Through 2 Cycle. Temperature Ramp:+1~4℃/sec; Above1 83℃, must keep 90 s - 120 s	MIL-STD-202G Method 210F Test Condition (Reflow)
Solder Ability Test	Soak in 245 ℃ solder pot of 3Sec, PAD must have 95% above coverage.	J-STD-003B

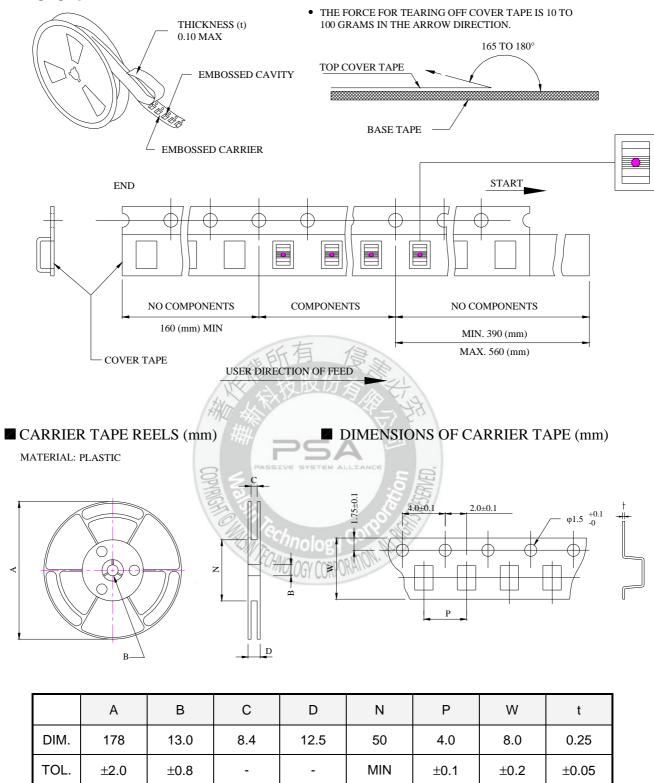


# **Typical RoHS Reflow Profile**





#### **Packaging Specification**



Quantity per reel: 3K pcs